UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/826,383	04/04/2001	Shigeyoshi Yoshida	0694-143	2904
75	90 05/28/2004		EXAM	INER
Hopgood, Cali	imafde, Judlowe & Mo	NGUYEN, KHIEM D		
New York, NY			ART UNIT	PAPER NUMBER
			2823	,
			DATE MAILED: 05/28/2004	4

Please find below and/or attached an Office communication concerning this application or proceeding.

		- BN
	Application No.	Applicant(s)
Office Action Summer.	09/826,383	SHIGEYOSHI YOSHIDA
Office Action Summary	Examiner	Art Unit
	Khiem D Nguyen	2823
Th MAILING DATE of this communication appeariod for Reply	pears on the cover sheet with the	e correspondenc address
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a rep - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute - Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b). Status	136(a). In no event, however, may a reply be ly within the statutory minimum of thirty (30) o will apply and will expire SIX (6) MONTHS fro a, cause the application to become ABANDO	timely filed days will be considered timely. om the mailing date of this communication. NED (35 U.S.C. § 133).
1) Responsive to communication(s) filed on 29	<u>March 2004</u> .	
2a)☐ This action is FINAL . 2b)⊠ The	nis action is non-final.	
3) Since this application is in condition for allow closed in accordance with the practice under Disposition of Claims	ance except for formal matters, Ex parte Quayle, 1935 C.D. 11	prosecution as to the ments is , 453 O.G. 213.
4) Claim(s) 1-42 is/are pending in the application	n.	
4a) Of the above claim(s) 22-28,32-34 and 39-	42 is/are withdrawn from consider	deration.
5) Claim(s) is/are allowed.		
6)⊠ Claim(s) <u>1-21,29-31 and 35-38</u> is/are rejected		
7) Claim(s) is/are objected to.		
8) Claim(s) are subject to restriction and/o	or election requirement.	
Application Papers		
9) The specification is objected to by the Examine		
10)⊠ The drawing(s) filed on <u>04 April 2001</u> is/are: a)		
Applicant may not request that any objection to the		
11) The proposed drawing correction filed on		Droved by the Examiner.
If approved, corrected drawings are required in re 12)☐ The oath or declaration is objected to by the Ex	•	
	Karrinter.	
Priority under 35 U.S.C. §§ 119 and 120	n nainaith cundan 25 11 0 0 °C 440	(A) (A) (B
13)⊠ Acknowledgment is made of a claim for foreig a)⊠ All b)□ Some * c)□ None of:	n priority under 35 0.5.C. § 118	g(a)-(g) or (t).
	to have been received	
 1.		ation No.
2. Certified copies of the priority document3. Copies of the certified copies of the priority		
application from the International Bu * See the attached detailed Office action for a list	ıreau (PCT Rule 17.2(a)).	-
14)☐ Acknowledgment is made of a claim for domest	ic priority under 35 U.S.C. § 11	9(e) (to a provisional application).
 a) ☐ The translation of the foreign language prediction 15)☐ Acknowledgment is made of a claim for domest 		
Attachment(s)		
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s) 5	5) Notice of Inform	ary (PTO-413) Paper No(s) al Patent Application (PTO-152)

Application/Control Number: 09/826,383

Art Unit: 2823

Page 2

DETAILED ACTION

Election/Restrictions

Applicant's election with traverse of claims 1-21, 29-31, and 35-38 in Paper No. 9 is acknowledged. The traversal is on the ground(s) that there is no time frame specified in the Group II claims, so when (the supposed "during the formation of the substrate") in the process the magnetic loss member is introduced is not an element of the method claims. This is not found persuasive because the product as claimed can be made by another and materially different process. In the instant case the product as claimed can be made by another and materially different process, such as introducing the magnetic loss member during the formation of the substrate. Group II claims required uniformly forming a film of the magnetic loss member on the substrate member after removing the insulating film pattern. Thus, there is time frame specified in the Group II claims.

Because these inventions are distinct for the reason given above and have acquired a separate status in the art as shown by their different classification.

The requirement is still deemed proper and is therefore made FINAL.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-21, 29-31, and 35-38 are rejected under 35 U.S.C. 102(e) as being anticipated by Awakura et al. (U.S. Patent 6,653,573).

In re claim 1, <u>Awakura</u> discloses a semiconductor bare chip having an integrated circuit formed on front surface thereof, wherein a magnetic loss film (FIG. 6: 65) is formed on back surface of the semiconductor bare chip (col. 8, lines 5-36 and FIGS. 6-7).

In re claim 2, <u>Awakura</u> discloses wherein the magnetic loss film is a granular magnetic thin film (col. 8, lines 5-24).

In re claim 3, <u>Awakura</u> discloses wherein the granular magnetic thin film is a sputtered film formed by a sputtering method (col. 9, line 48 to col. 10, line 12).

In re claim 4, <u>Awakura</u> disclose wherein the granular magnetic thin film is a vapor-deposited film formed by a vapor deposition method (col. 7, lines 2-22).

In re claim 5, <u>Awakura</u> disclose wherein a magnetic loss film is formed on back surface of the semiconductor wafer (FIGS. 6-7).

In re claim 6, Awakura discloses wherein the magnetic loss film is a granular magnetic thin film (FIG. 6: 65) (col. 8, lines 5-36).

In re claim 7, <u>Awakura</u> discloses wherein the granular magnetic thin film is a sputtered film formed by a sputtering method (col. 9, line 48 to col. 10, line 12).

In re claim 8, <u>Awakura</u> discloses wherein the granular magnetic thin film is a vapor-deposited film formed by a vapor deposition method (col. 7, lines 2-22).

In re claim 9, <u>Awakura</u> discloses wherein the magnetic loss member (FIG. 6: 65) is formed in a prescribed pattern in vicinity of the surface on one side of the

semiconductor substrate; and the magnetic loss member and semiconductor substrate region on the surface are uniformly covered with an insulating film (FIG. 7: 71) (col. 9, lines 22-29).

In re claim 10, <u>Awakura</u> discloses wherein the magnetic loss member (FIG. 6: 65) is formed over substantially entire surface of the semiconductor substrate (FIGS. 6-7).

In re claim 11, <u>Awakura</u> discloses wherein the prescribed pattern is formed by the magnetic loss member and is a striped pattern (FIGS. 6-7).

In re claim 12, <u>Awakura</u> discloses wherein the prescribed pattern is formed by the magnetic loss member and is a lattice pattern (FIGS. 6-7).

In re claim 13, <u>Awakura</u> discloses wherein the prescribed pattern is formed by the magnetic loss member and is an island pattern (FIGS. 6-7).

In re claim 14, <u>Awakura</u> discloses wherein the insulating film comprises at least one material selected from a group consisting of silicon oxide, silicon nitride, and silicon nitride oxide (col. 9, lines 22-29).

In re claim 15, <u>Awakura</u> discloses a semiconductor substrate having a plurality of magnetic loss members (FIG. 6: 65) formed in a part thereof, wherein said magnetic loss members are formed in a prescribed pattern, each of the magnetic loss members being formed on an inside surface of each semiconductor device region which is separated by dividing the semiconductor substrate (FIGS. 6-7).

In re claim 16, <u>Awakura</u> discloses a semiconductor substrate formed by joining a first semiconductor substrate member and a second semiconductor substrate member

together, and having a magnetic loss member (FIG. 6: 65) formed in a part thereof (FIGS. 6-7), wherein at least one semiconductor substrate member of the first semiconductor substrate member and the second semiconductor substrate member is provided with a trench, which is formed on the surface thereof that is joined together, and the magnetic loss member is embedded inside said trench (col. 8, lines 5-36 and FIGS. 6-7).

In re claim 17, <u>Awakura</u> discloses wherein the trench comprises a plurality of trench portions formed in a prescribed pattern, each of the trench portions being formed on an inside surface of each semiconductor device region which is separated by dividing the semiconductor substrate (col. 8, lines 5-36 and **FIGS. 6-7**).

In re claim 18, <u>Awakura</u> discloses wherein said magnetic loss member is composed of M-X-Y, where M is either any one of, or a mixture of, Fe, Co, and Ni, X is either an element other than M and Y or a mixture thereof, and Y is any one of, or a mixture of, F, N, and O (col. 12, lines 42-58).

In re claim 19, <u>Awakura</u> discloses wherein material of the semiconductor substrate, the first semiconductor substrate member, and the second semiconductor substrate member, respectively, consists of silicon (col. 8, lines 5-36 and FIGS. 6-7).

In re claim 20, <u>Awakura</u> discloses wherein material of the semiconductor substrate, the first semiconductor substrate member, and the second semiconductor substrate member, respectively, consists of gallium-arsenic (col. 8, lines 5-36 and FIGS. 6-7).

In re claim 21, Awakura discloses a plurality of semiconductor devices that is repeatedly formed in a prescribed pattern on the semiconductor substrate according to claim 9, wherein each of the plurality of semiconductor devices comprises at least one unit region in which the magnetic loss member is formed (col. 8, lines 5-36 and FIGS. 6-7).

In re claim 29, <u>Awakura</u> discloses an electromagnetic noise suppression body comprising an electrically conductive soft magnetic thin film; and having a structure, wherein said soft magnetic thin film is finely divided into configuring units sufficiently small relative to wavelength of electromagnetic noise; and conduction of DC current between those configuring units is interrupted (col. 7, line 2 to col. 8, line 36).

In re claim 30, Awakura discloses wherein the soft magnetic thin film has an aspect ratio of 10 or greater (col. 7, line 2 to col. 8, line 36).

In re claim 31, Awakura discloses wherein the soft magnetic thin film is composed of a composition of M-X-Y, where M is either any one of, or a mixture of, Fe, Co, and Ni, X is either an element other than M and Y or a mixture thereof, and Y is any one of, or a mixture of, F, N, and 0, and has a granular structure (col. 12, lines 42-58).

In re claim 35, Awakura discloses an electromagnetic noise suppression body for suppressing conductive electromagnetic noise, comprising an electrically conductive soft magnetic thin film attached in vicinity above a microstrip line or signal transmission line similar thereto, wherein the electrically conductive soft magnetic thin film is of a shape having a width that is substantially equivalent to or narrower than line width of the

microstrip line or signal transmission line similar thereto (col. 10, line 66 to col. 12, line 17).

In re claim 36, <u>Awakura</u> discloses wherein the electromagnetic noise suppression body is attached so that the axis of hard magnetization thereof is substantially parallel to the width direction of the microstrip line or signal transmission line similar thereto (col. 11, line 22 to col. 12, line 17 and **FIG. 11**).

In re claim 37, <u>Awakura</u> discloses wherein the soft magnetic thin film of a shape having a width that is substantially equivalent to or narrower than line width of the microstrip line or analogous signal transmission line has an aspect ratio in width direction of 10 or greater (col. 7, line 2 to col. 8, line 36).

In re claim 38, <u>Awakura</u> discloses wherein the soft magnetic thin film is composed of a composition of M-X-Y, where M is either any one of, or a mixture of, Fe, Co, and Ni, X is either an element other than M and Y or a mixture thereof, and Y is any one of, or a mixture of, F, N, and 0, and has a granular structure (col. 12, lines 42-58).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D Nguyen whose telephone number is (571) 272-1865. The examiner can normally be reached on Monday-Friday (8:00 AM - 5:00 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on (571) 272-1855. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 305-3432 for regular communications and (703) 305-3432 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

K.N. May 25, 2004

> W. DAVID COLEMAN PRIMARY EXAMINER

Please type a plus sign (+) inside this box

Approved for use through 10/31/99. OMB 0651-0031

Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet	1	of	2
-------	---	----	---

		THE E TAILS ON B	control trainber.
C	ompl t if K	nown	
Application Number		09/826,383	
Filing Date		04/04/2001	
First Named Inventor	8	higeyoshi Yos	hida
Group Art Unit		2815	2823
Examiner Name	Khiam	AKA	Nauven
Attorney Docket Number		0694-143	00

				U.S. PATENT DOC	JMENTS	
Examiner Initials*	Cite No.1	U.S. Patent Number	Document Kind Code ² (if known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
K.N.		3,783,499			01-08-1974	Tigures Appear
K.V.		5,373,627		Kurt R. Grebe	12-20-1994	
KN.		5,408,123		Takashi Murai	04-18-1995	
K.N.		5,831,324		H-soon Bang	11-03-1998	
				· · · · · · · · · · · · · · · · · · ·		
-		_				<u> </u>
-						
						- E

				FOR	EIGN PATENT DOCUMEN	TS		
Examiner Initials*	Cite No.1	Office	Foreign Patent Do	Coument Kind Code ⁵ (if known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
KN.		JP	10128140		Sato Mitsuharu	11-05-1999		
K.H.	-	EP	0 785 557	A1	Shigeyoshi Yoshida	07-23-1997		
								П

	Examiner Signature	He enough work	Date Considered	02/32/04	
--	-----------------------	----------------	--------------------	----------	--

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

PTO/SB/08B (10-96)

Approved for use through 10/31/99. OMB 0651-0031

Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 2 of 2

The state of the s						
Co	Complete if Known					
Application Number	09/826,383					
Filing Date	04/04/2001					
First Named Inventor	Shigeyoshi Yoshida					
Group Art Unit	2845 2823					
Examiner Name	Kliem MA D. Namen					
Attorney Docket Number	0694-143					

		OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
K.N.		Copy of European Search Report dated 8/13/2001	
,			
		CT 18 200	
		8 2001 EHILK 2000	
		\$ 100 m	
	<u> </u>		+-
Examine		Date Considered Considered	

*EXAMINER: Initial if reference considered, whether of not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

¹ Unique citation designation number. ² Applicant is to place a check mark here if English language Translation is attached.

Notice of References Cited Application/Control No. O9/826,383 Applicant(s)/Patent Under Reexamination SHIGEYOSHI YOSHIDA Examiner Khiem D Nguyen Art Unit Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,653,573	11-2003	Awakura et al.	174/256
*	В	US-6,719,615	04-2004	Molnar, Charles J.	451/41
*	C	US-6,515,352	02-2003	Spielberger et al.	257/659
*	D	US-6,452,253	09-2002	Tuttle, Mark	257/659
*	E	US-5,639,989	06-1997	Higgins, III, Leo M.	174/35MS
*	F	US-3,963,489	06-1976	Cho, Kon Ho	430/22
*	G	US-5,698,284	12-1997	Kubota et al.	428/64.7
	Н	US			
	1	US-			
	J	US-			
	К	US-			
	L	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р					
	ď					
	R					
	s					
	Т					

NON-PATENT DOCUMENTS

	,	
*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	
	٧	
	w	
	х	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

Organization Bldg./Room_U. S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
WASHINGTON, DC 20231
IF UNDELIVERABLE RETURN IN TEN DAYS

OFFICIAL BUSINESS

AN EQUAL OPPORTUNITY EMPLOYER





JUN 28 2004 TECHNOLOGY CENTER 2800

BEST AVAILABLE COP